



5NM90

Preliminary

Power MOSFET

5A, 900V N-CHANNEL SUPER-JUNCTION MOSFET

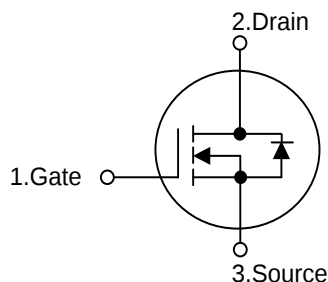
DESCRIPTION

The **UTC 5NM90** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

FEATURES

- * $R_{DS(ON)} \leq 2.5 \Omega$ @ $V_{GS}=10V$, $I_D=2.5A$
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness

SYMBOL

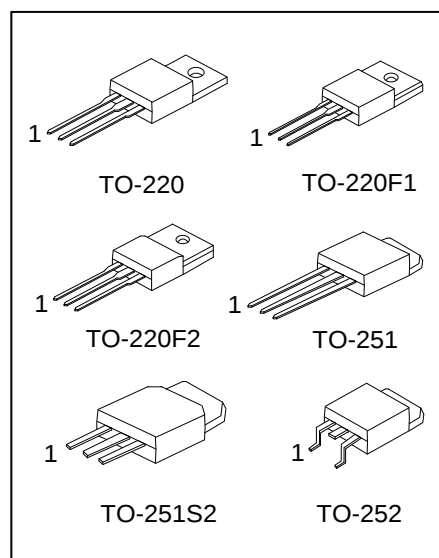


ORDERING INFORMATION

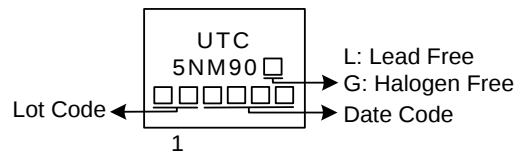
Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
5NM90L-TA3-T	5NM90G-TA3-T	TO-220	G	D	S	Tube
5NM90L-TF1-T	5NM90G-TF1-T	TO-220F1	G	D	S	Tube
5NM90L-TF2-T	5NM90G-TF2-T	TO-220F2	G	D	S	Tube
5NM90L-TM3-T	5NM90G-TM3-T	TO-251	G	D	S	Tube
5NM90L-TMS2-T	5NM90G-TMS2-T	TO-251S2	G	D	S	Tube
5NM90L-TN3-R	5NM90G-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

5NM90G-TA3-T (1) Packing Type (2) Package Type (3) Green Package		(1) T: Tube, R: Tape Reel (2) TA3: TO-220, TF1: TO-220F1, TF2: TO-220F2 TM3: TO-251, TMS2: TO-251S2, TN3: TO-252 (3) G: Halogen Free and Lead Free, L: Lead Free
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■ MARKING



■ **ABSOLUTE MAXIMUM RATINGS** ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	900	V
Gate-Source Voltage		V_{GSS}	± 30	V
Continuous Drain Current	Continuous	I_D	5.0	A
Pulsed Drain Current	Pulsed (Note 2)	I_{DM}	20	A
Avalanche Current (Note 2)		I_{AR}	1.5	A
Single Pulsed Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	179	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	1.6	V/ns
Power Dissipation	TO-220	P_D	45	W
	TO-220F1/TO-220F2		25	W
	TO-251S2/TO-251		37	W
	TO-252			
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $L = 159\text{mH}$, $I_{AS} = 1.5\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.

4. $I_{SD} \leq 5.0\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$.

■ **THERMAL DATA**

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-220/TO-220F1	θ_{JA}	62.5	$^\circ\text{C/W}$
	TO-220F2			
	TO-251S2/TO-251		110	$^\circ\text{C/W}$
	TO-252			
Junction to Case	TO-220	θ_{JC}	2.78	$^\circ\text{C/W}$
	TO-220F1/TO-220F2		5	$^\circ\text{C/W}$
	TO-251S2/TO-251		3.38 (Note)	$^\circ\text{C/W}$
	TO-252			

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

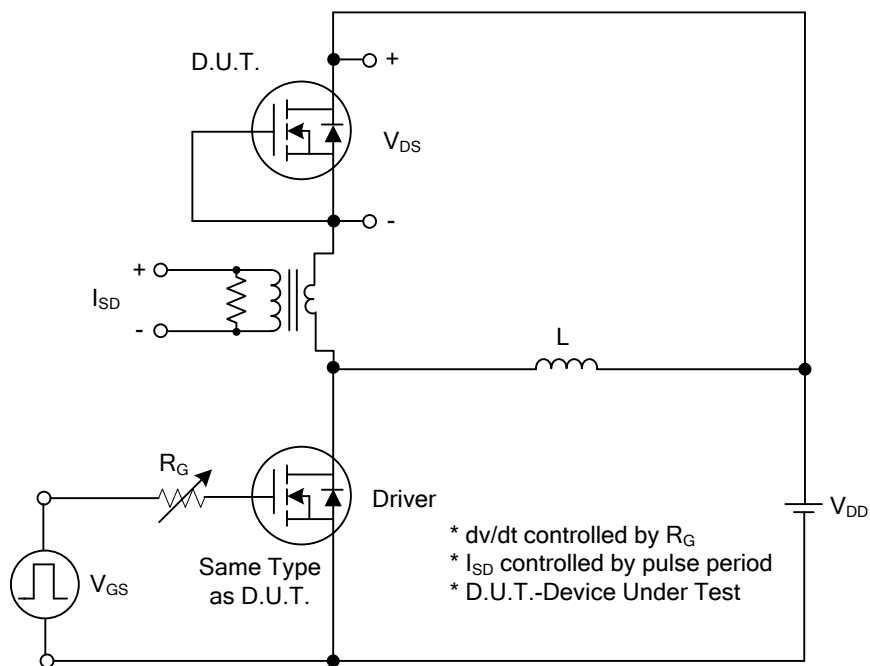
■ **ELECTRICAL CHARACTERISTICS** ($T_J = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} = 0V, I _D = 250μA	900			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} = 900V, V _{GS} = 0V			10	μA
Gate-Source Leakage Current	Forward	I _{GSS}	V _{GS} = 30V, V _{DS} = 0V			100	nA
	Reverse		V _{GS} = -30V, V _{DS} = 0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} = V _{GS} , I _D = 250μA	2.5		4.5	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} = 10V, I _D = 2.5A			2.5	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{ISS}	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		380		pF
Output Capacitance		C _{OSS}			160		pF
Reverse Transfer Capacitance		C _{RSS}			8		pF
SWITCHING CHARACTERISTICS							
Total Gate Charge (Note 1)		Q _G	V _{DS} =50V, I _D =1.3A, I _G =100μA V _{GS} =10V (Note 1,2)		47		nC
Gate to Source Charge		Q _{GS}			4		nC
Gate to Drain Charge		Q _{GD}			12		nC
Turn-ON Delay Time (Note 1)		t _{D(ON)}	V _{DD} =30V, I _D =0.5A, R _G =25Ω, V _{GS} =10V (Note 1,2)		40		nS
Rise Time		t _R			70		nS
Turn-OFF Delay Time		t _{D(OFF)}			180		nS
Fall-Time		t _F			45		nS
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Body-Diode Continuous Current		I _S				5.0	A
Maximum Body-Diode Pulsed Current		I _{SM}				20	A
Drain-Source Diode Forward Voltage (Note 1)		V _{SD}	I _S =5.0A, V _{GS} =0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)		t _{rr}	I _S =5.0A, V _{GS} =0V,		520		nS
Body Diode Reverse Recovery Charge		Q _{rr}	dl _F /dt=100A/μs		4.65		μC

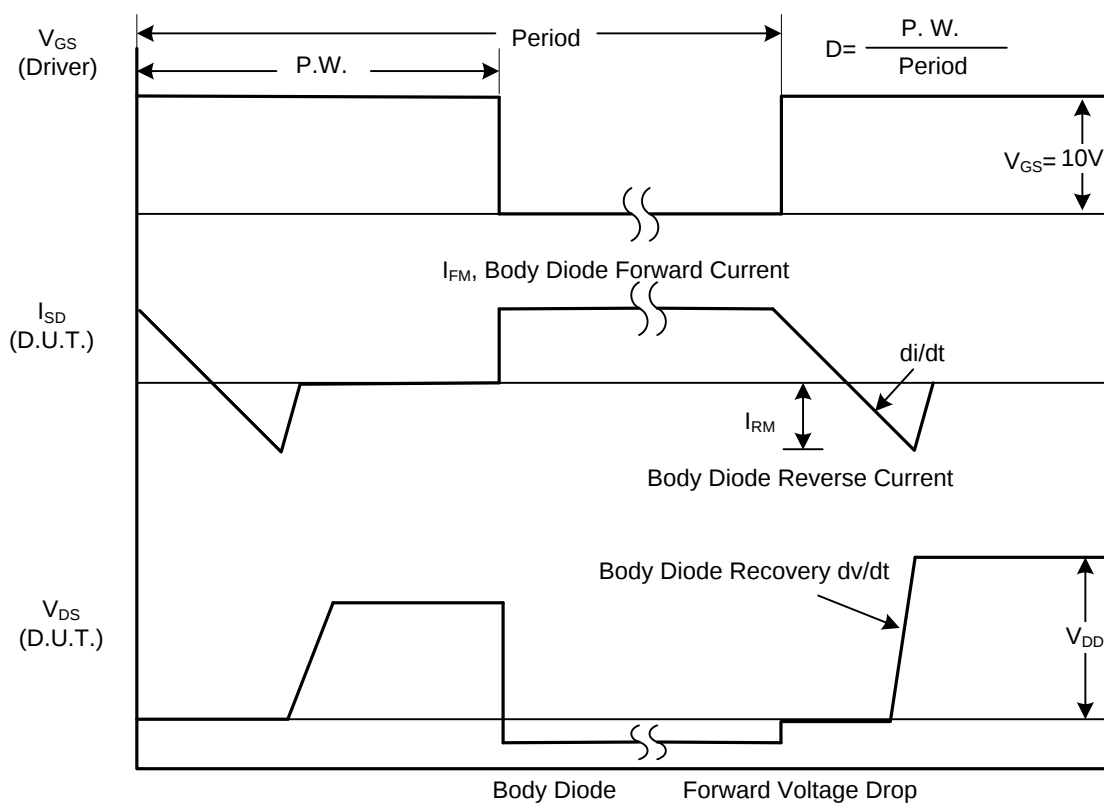
Notes: 1. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS

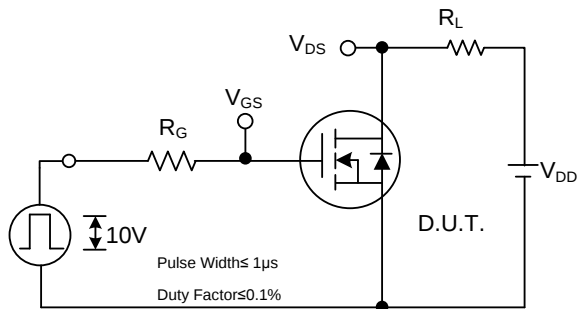


Peak Diode Recovery dv/dt Test Circuit

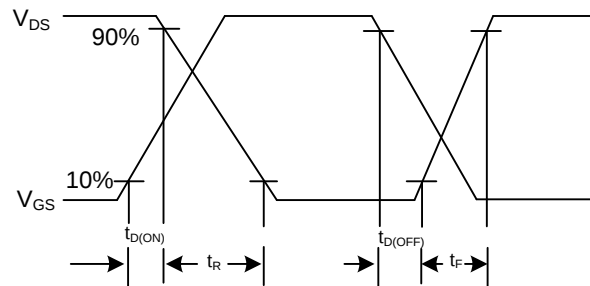


Peak Diode Recovery dv/dt Waveforms

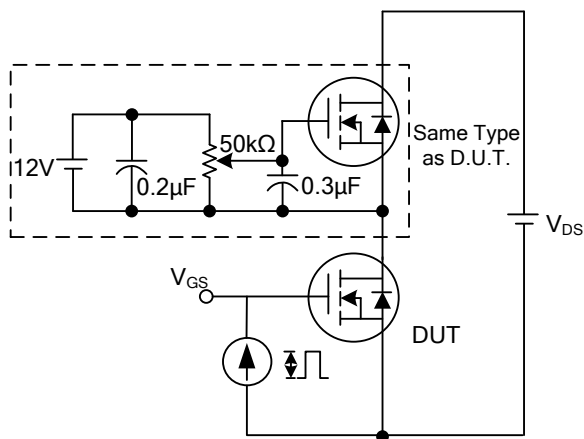
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



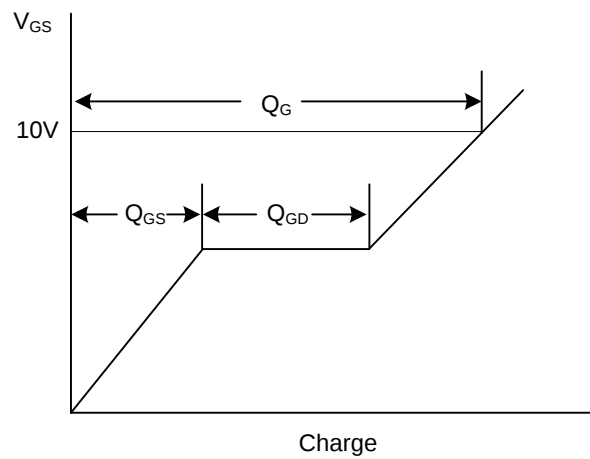
Switching Test Circuit



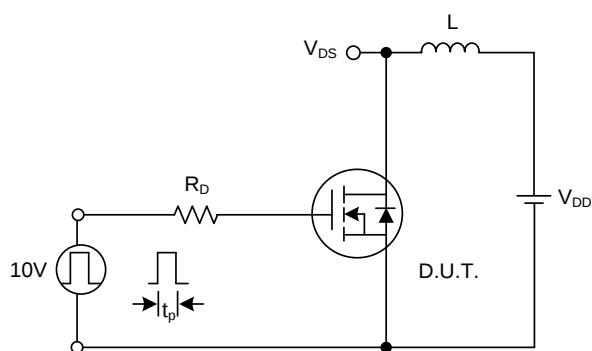
Switching Waveforms



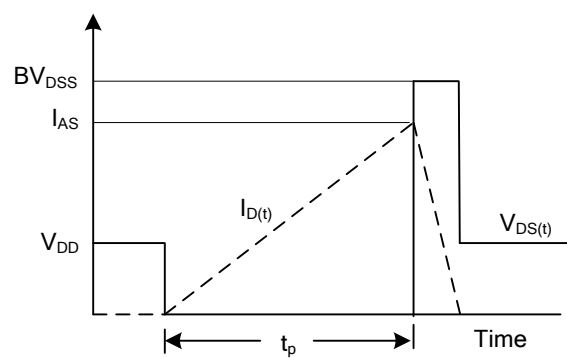
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

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